## **REMARKS**

In view of the above amendments and following remarks, reconsideration and further examination are requested.

In the final rejection mailed September 26, 2005, claims 1, 10-15 and 22-33 were rejected under 35 U.S.C. § 102(b) as being anticipated by EP '387, and, claims 1, 10-15 and 22-33 were rejected under 35 U.S.C. § 102(e) as being anticipated by Katsuoka et al.

In order to read claim 1 on EP '387, the Examiner apparently construed a combination of cleaning units 8a and 8b to correspond to the claimed "common second cleaning unit". Similarly, with regard to Katsuoka et al., the Examiner apparently equated a combination of cleaning units 14a and 14b to the claimed "common second cleaning unit". Accordingly, by the current Amendment claim 1 has been amended so as to prevent the claimed "common second cleaning unit" from being corresponded to the two separate cleaning units 8a and 8b of EP '387, or the two separate cleaning units 14a and 14b of Katsuoka et al.

In this regard, claim 1 now recites:

A method of polishing and then cleaning substrates, comprising:

polishing a first substrate by pressing said first substrate against a first polishing surface; then

primarily cleaning said first substrate in a first of two first cleaning units; then

secondarily cleaning said first substrate in a common second cleaning unit while supporting said first substrate on a table;

polishing a second substrate by pressing said second substrate against a second polishing surface; then

primarily cleaning said second substrate in a second of said two first cleaning units; and then

secondarily cleaning said second substrate in said common second cleaning unit while supporting said second substrate on said table.

Thus, claim 1 requires that the same table is used to support each of the first and second substrates during cleaning thereof, whereas in EP '387 and Katsuoka et al. separate tables or

support members associated with the cleaning units (8a and 8b in EP '387, and 14a and 14b of Katsuoka et al.) are used to support first and second substrates, respectively, during cleaning thereof. Accordingly, because the same table or support member is not used to support substrates (polished by different polishing surfaces) during cleaning of these substrates, a method including utilization of a "common second cleaning unit" as required by claim 1 is not taught or suggested by neither EP '387 nor Katsuoka et al.

Thus, claims 1, 10-15 and 22-34 are allowable.

In view of the above amendments and remarks, it is respectfully submitted that the present application is in condition for allowance and an early Notice of Allowance is earnestly solicited.

If after reviewing this Amendment, the Examiner believes that any issues remain which must be resolved before the application can be passed to issue, the Examiner is invited to contact the Applicants' undersigned representative by telephone to resolve such issues.

Respectfully submitted,

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